-	THE TAILUI APPLICATION	(WITH POWER (TOKNEY)		
My residence, post office address an	any a sed continuation page, I hereby declare the distribution of	•		•
I believe that I am the original, first below) of the subject matter which is cla	and sole inventor (if only one name is listed belo simed and for which a patent is sought on the inv	ention entitled PLASTIC I FAD FD AMES E	plural names	are listed
DEVICES, PACKAGES INCLUDING	SAME, AND METHODS OF FABRICATION,	the specification of which (check one):	OK SEMICO	NEUCTO
s is attached hereto.				
D was filed onas Un	ited States application serial noand	was amended on .		
us filed onas PC	ited States application serial no. and T international application no. and v	vas amended under PCT Article 19 on	•	
	nd understand the contents of the above-identified			nesidment
I acknowledge the duty to disclose to matter claimed in this application, as "m	the U.S. Patent and Trademark Office all informateriality" is defined in Title 37, Code of Federa	nation known to me to be material to the pate I Regulations § 1.56.	entability of th	e subject
attached continuation page and have also	s under Title 35, United States Code, § 119 (a)-(a ational application(s) designating at least one cou identified below and on any attached continuatio gnating at least one country other than the United d.	ntry other than the United States of America	listed below	
Prior foreign/PCT application(s):	7		Priority C	Iaimed
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)	Yes	No
Regulations § 1.56 which became available (application serial no.)	Trademark Office all information known to me between the filing date of such prior application (filing date)	n and the national or PCT international filing	g date of this	of Federa application
	(ming date)	(status - pending, patented or a	ibandoned)	
(application serial no.)	(filing date)	(status - pending, patented or s	bandoned)	
hereby claim the benefit under Title 35	5, United States Code, § 119(e) of any United St		-	
(provisional application no.)	(filing date)			
(provisional application no.)	(filing date)		,	
(provisional application no.)	(filing date)			
I hereby appoint the following Registers connected therewith:	ed Practitioners to prosecute this application and	to transact all business in the Patent and Tra	ademark Offic	•
David V. Trask, Reg. No. 22,012 Laurence B. Bond, Reg. No. 30,549 Allen C. Turner, Reg. No. 33,041 Robert G. Winkle, Reg. No. 37,474 Michael L. Lynch, Reg. No. 30,871	William S. Britt, Reg. No. 20,969 Joseph A. Walkowski, Reg. No. 28,765 Kent S. Burningham, Reg. No. 30,453 Patrick McBride, Reg. No. 39,295 Lia M. Pappas, Reg. No. 34,095	Thomas J. Rossa, Reg. No. 26,799 James R. Duzan, Reg. No. 28,393 Julie K. Morriss, Reg. No. 33,263 Edgar R. Cataxinos, Reg. No. 39,931		
P.	nmes R. Duzan, telephone no. (801) 532-1922. RASK, BRITT & ROSSA O. BOX 2550 alt Lake City, Utah 84110			
I hereby declare that all statements made true; and further that these statements were	herein of my own knowledge are true and that made with the knowledge that willful false state he United States Code and that such willful false	ments and the like so made are numichable t		•
Full name of first joint inventor: Tongbi Jie Inventor's signature	ang Sc	Date6/13/97		
Residence: Boise, Idaho Citizenship: P.R. China Post Office Address: 197 E. Mallard Drive	, #225, Boise, ID 83706			-

DECLARATION FOR PATENT APPLICATION

Internation title: PLASTIC LEAD FRAMES FOR SEMICONDUCTOR DEVICES, PACKAGES INCLUDING SAME, AND METHODS OF FABRICATION

Inventor name(s) appearing on first declaration page: Tongbi Jiang

Additional original, first and joint inventor(s):

Full name of second joint inventor: Jerrold L. King

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